描述 / Descriptions

表面贴装整流二极管，反向电压：50V~1000V，正向电流：3.0A，薄型 SMBF 封装。
Surface Mount General Purpose Silicon Rectifiers,Reverse Voltage:50 to1000V,Forward Current:3.0A, SMBF thin package.

特征 / Features

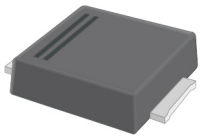
玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用于表面贴装。无卤产品。
Glass Passivated Chip Junction, Lead free in comply with EU R0HS 2011/65/EU directives, For surface mounted applications. Halogen free product.

用途 / Applications

一般用途.
General purpose.

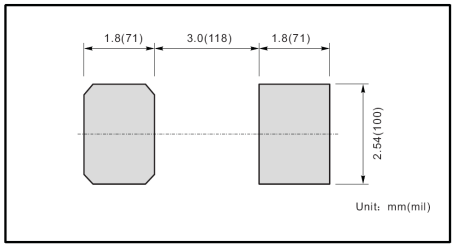
内部等效电路 / Equivalent Circuit

引脚排列 / Pinning

1  2

PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25℃)

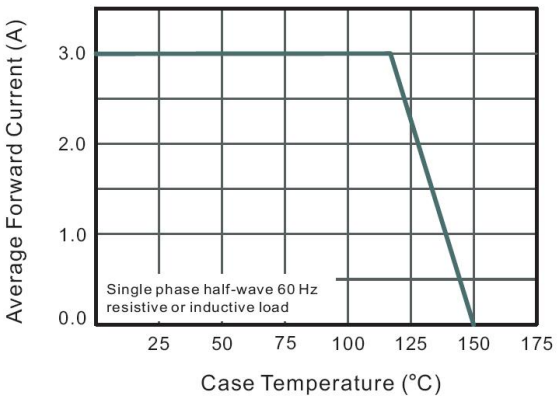
参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S3ABF	S3BBF	S3DBF	S3GBF	S3JBF	S3KBF	S3MBF	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T_a= 115℃	$I_{F(AV)}$	3.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	100							A
Typical Junction Capacitance [1]	C_j	35							pF
Typical Thermal Resistance [2]	$R_{\theta JA}$ $R_{\theta JC}$	45 15							℃/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~+150							℃

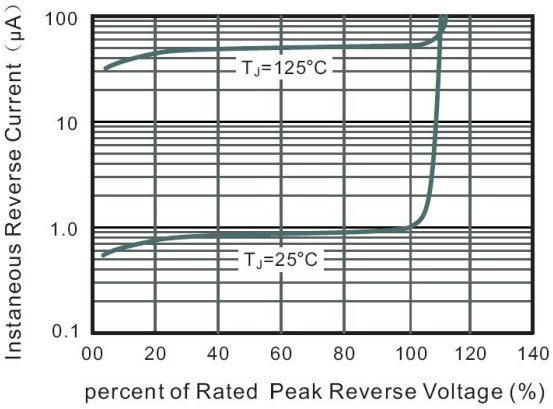
Note:
1）Measured at 1MHz and applied reverse voltage of 4V D.C
2）P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

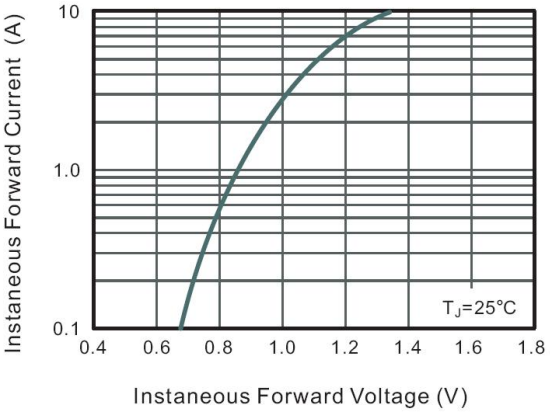
电性能参数 / Electrical Characteristics(Ta=25℃)

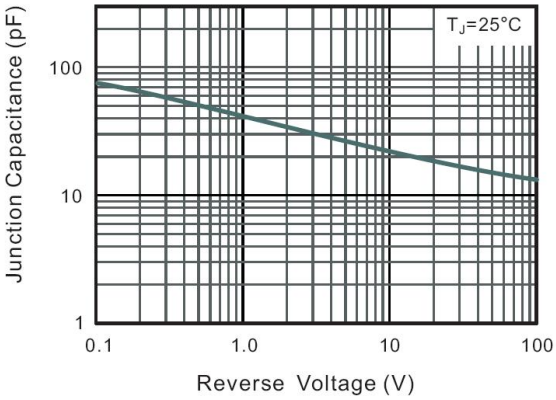
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Maximum Forward Voltage	V_F	I_F=3.0A	1.1	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	T_a=25℃	5.0	μA
		T_a=125℃	150	μA

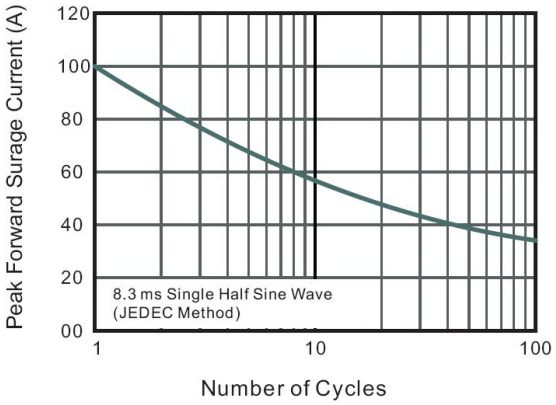
电参数曲线图 / Electrical Characteristic Curve





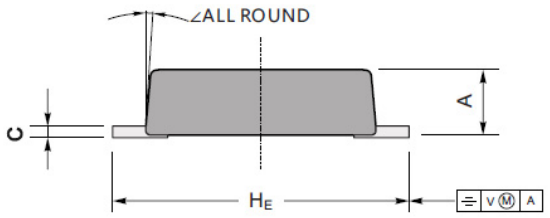


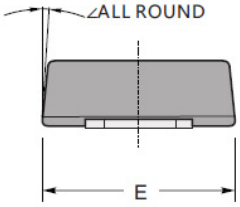


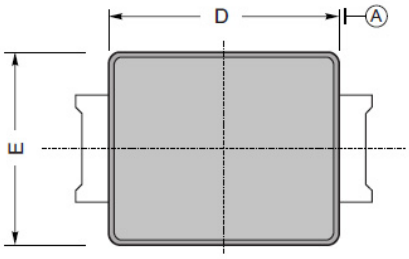


外形尺寸图 / Package Dimensions

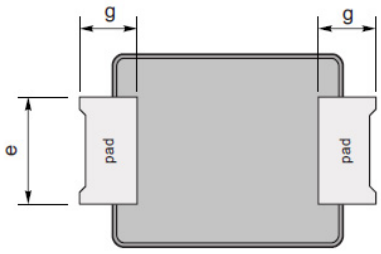
SMBF







Top View



Bottom View

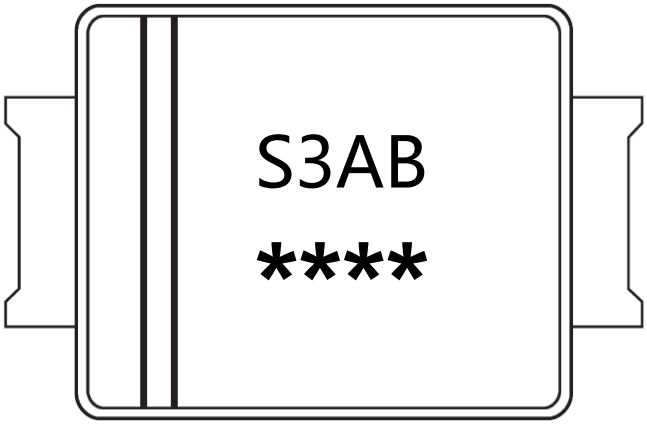
UNIT		A	C	D	E	H_E	e	g	∠
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	9°
	min	1.1	0.18	4.2	3.5	5.1	1.9		
mil	max	51	10	173	146	216	86	40	
	min	43	7	165	138	200	75		

印章说明 / Marking Instructions

Marking

Type number	Marking code
S3ABF	S3AB
S3BBF	S3BB
S3DBF	S3DB
S3GBF	S3GB
S3JBF	S3JB
S3KBF	S3KB
S3MBF	S3MB

印章说明 / Marking Instructions



说明：

S3AB： 为型号代码

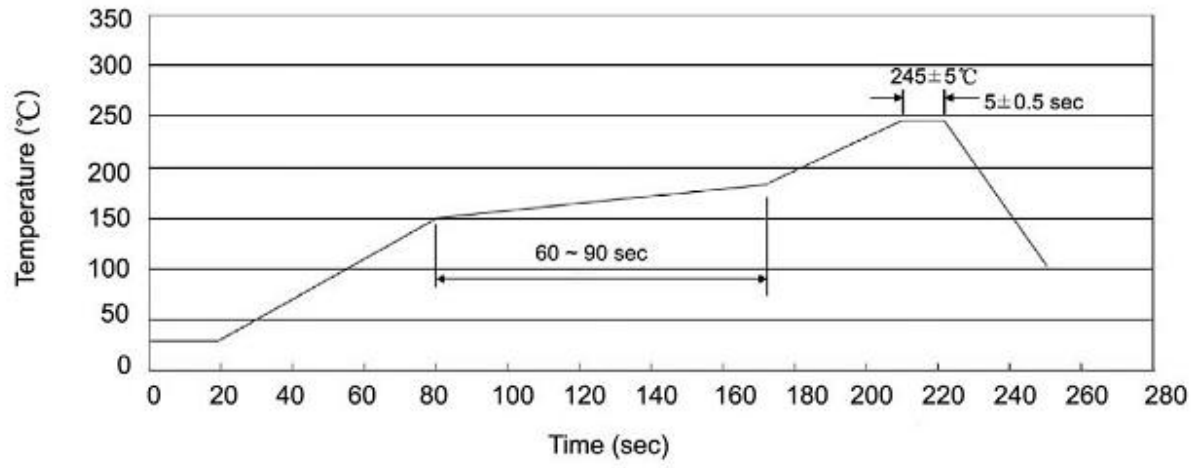
**** ： 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

Note:

S3AB： Product Type Code

****： Lot No. Code，The 1st * means:YM Code，The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

1、预热温度 150～180℃，时间 60～90sec;

2、峰值温度 245±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:150~180℃, Time:60~90sec.

2.Peak Temp.:245±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp.:260±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMBF	5000	2	10000	5	50000	13″ ×15	336X332X40	380X335X366

使用说明 / Notices